

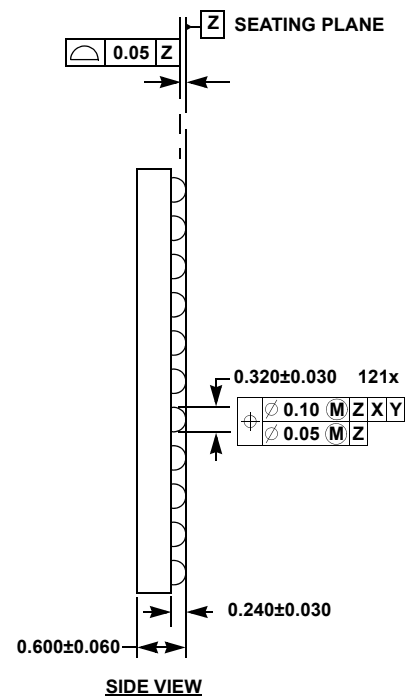
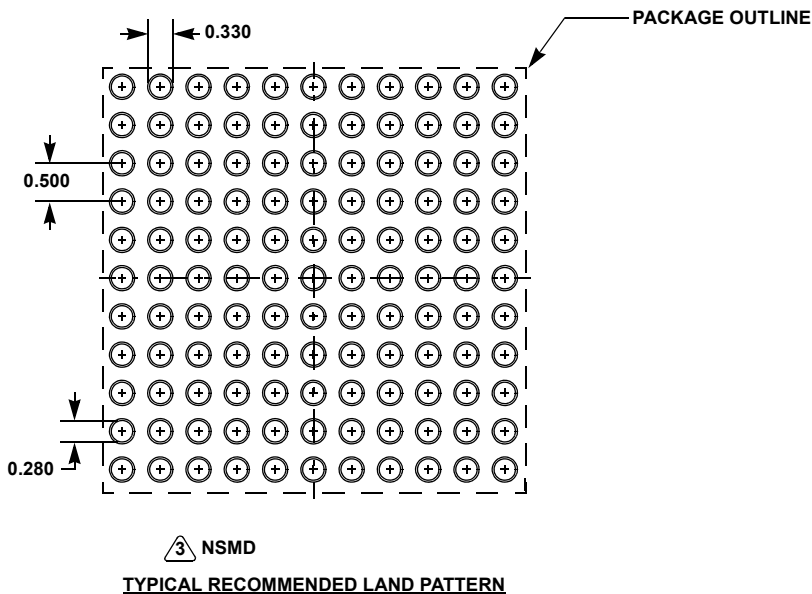
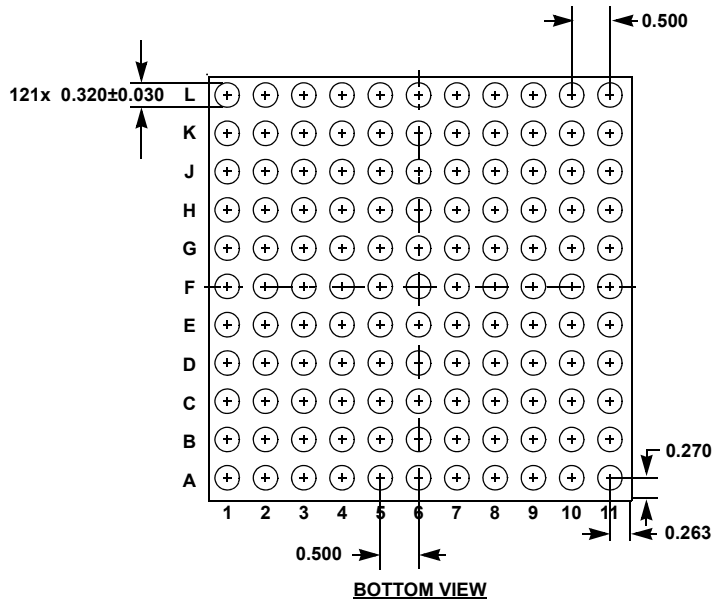
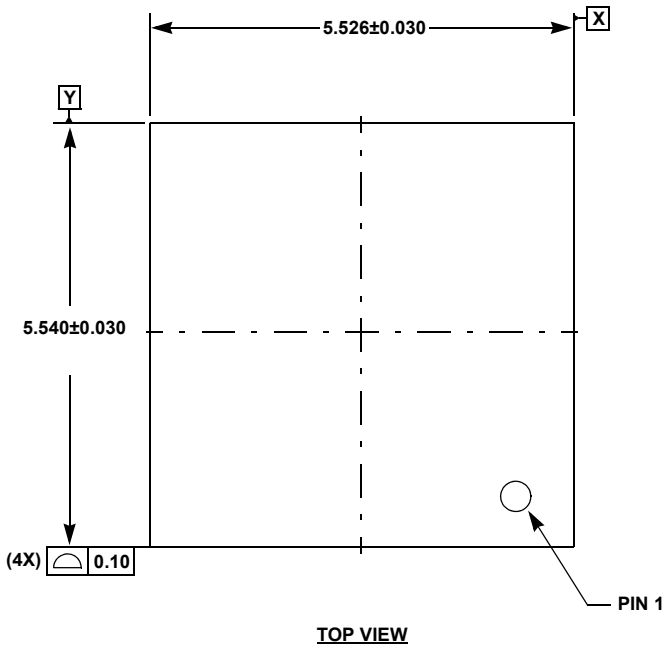
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### W11x11.121B

121 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.5mm pitch)

Rev 0, 2/14



#### NOTES:

1. All dimensions are in millimeters.
  2. Dimensions and tolerance per ASMEY 14.5M - 1994 and JESD 95-1, SPP-010.
- Ⓜ NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).